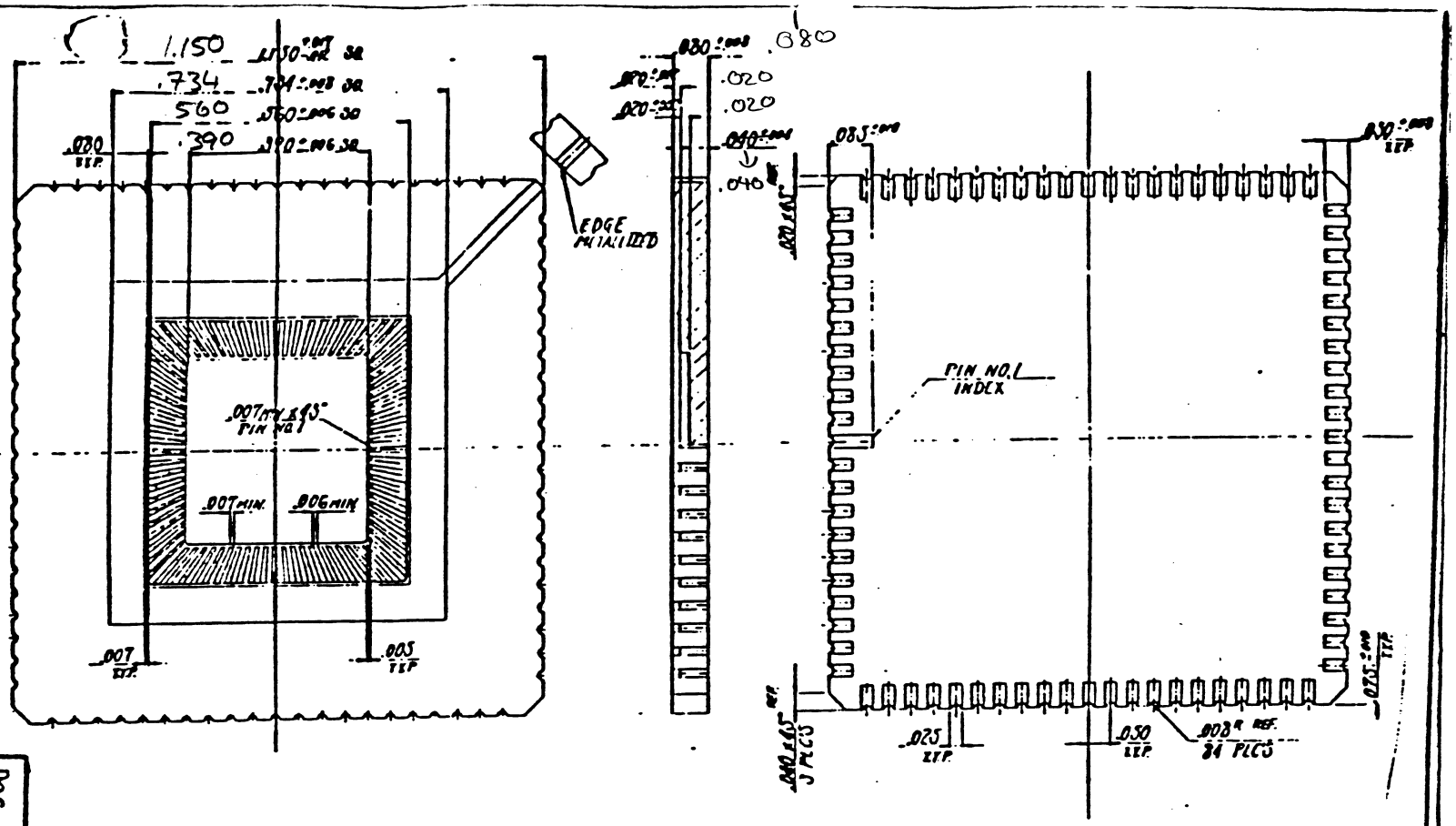

NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD

DOCUMENT CONTROL RELEASED
SPEC CENTER # 1

Doc. No.

Sheet 01

CHANGE	DATE	PROD			NAME: 84 LEAD CHIP CARRIER			NG-84CA
					SCALE 6/1	MATERIAL CERAMIC KYOCERA A-440	21%	78-8-25
					KYOTO CERAMIC CO., LTD. KYOTO JAPAN			PB-81911